100% Material Declaration Data Sheet BG256

Average Weight: 2.8727 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					**0.0735**	**2.56%**
	Silicon	7440-21-3	100.00		0.0735	
Die Attach Material					**0.0073**	**0.25%**
	Resin	Trade Secret	22.00		0.0016	
	Silver	7440-22-4	78.00		0.0057	
Mold Compound					**1.0846**	**37.76%**
	Resin	Trade Secret	12.00		0.1302	
	Silica	60676-86-0	88.00	Filler	0.9544	
Laminate					**1.1403**	**39.69%**
	Laminate	Trade Secret			0.5613	
	Solder Mask (EP)	Trade Secret			0.0878	
	Copper	7440-50-8		Metal Layer	0.4662	
	Nickel	7440-02-0		Metal Layer	0.0209	
	Gold	7440-57-5		Metal Layer	0.0041	
Gold Wire					**0.0134**	**0.47%**
	Gold	7440-57-5	100.00		0.0134	
Solder Balls					**0.5536**	**19.27%**
	Tin	7440-31-5	63.00		0.3488	
	Lead	7439-92-1	37.00		0.2048	

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Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
3/23/06	1.0	Initial release.
7/12/06	1.1	100% Material Declaration.
9/28/06	1.2	Updated component descriptions.
1/8/07	1.2.1	Corrected Gold Wire CAS# entry.

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